



ABSTRACT

Microelectronic contact structures comprise palladium or a palladium-cobalt alloy. Each contact structure may have three components: a "post" component, a "beam" component, and a "tip" component. The resulting contact structure, mounted to an electronic component, is useful for making an electrical connection with another electronic component. The post component can be fabricated on a sacrificial substrate, joined to the electronic component and its sacrificial substrate removed. Alternatively, the post component can be formed on the electronic component. The beam and tip components can each be fabricated on a sacrificial substrate. The beam component is joined to the post component and its sacrificial substrate is removed, and the tip component is joined to the beam component and its sacrificial substrate is removed.